



Material Content Data Sheet



Sales Product Name		IDD10SG60C		Issued		29. August 2013		
MA#		MA000809456						
Package		PG-TO252-3-311		Weight*		312.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.143	0.05		457	
	non noble metal	tin	7440-31-5	0.037	0.01		118	
	inorganic material	silicon	7440-21-3	1.816	0.58	0.64	5816	6391
leadframe	non noble metal	iron	7439-89-6	0.162	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.049	0.02		156	
	non noble metal	copper	7440-50-8	162.275	51.97	52.04	519778	520455
wire	non noble metal	aluminium	7429-90-5	0.931	0.30	0.30	2981	2981
encapsulation	organic material	carbon black	1333-86-4	1.430	0.46		4579	
	plastics	epoxy resin	-	25.018	8.01		80135	
	inorganic material	silicondioxide	60676-86-0	116.514	37.32	45.79	373201	457915
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11980	11980
plating	non noble metal	nickel	7440-02-0	0.086	0.03		277	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	278
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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